

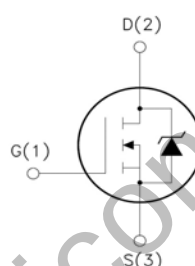
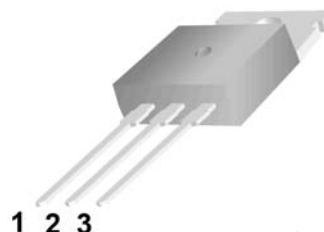


WGP9N90

Features:

- ☐ Low Intrinsic Capacitances.
- ☐ Excellent Switching Characteristics.
- ☐ Extended Safe Operating Area.
- ☐ Unrivalled Gate Charge: $Q_g = 45\text{nC}$ (Typ.).
- ☐ $BVDSS = 900\text{V}$, $I_D = 9\text{A}$
- ☐ $R_{DS(on)} : 1.4\Omega$ (Max) @ $V_G = 10\text{V}$
- ☐ 100% Avalanche Tested

TO-220



- 1. Gate (G)
- 2. Drain (D)
- 3. Source (S)

Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	900	V
I_D	Drain Current	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
$V_{GS(TH)}$	Gate Threshold Voltage	± 30	V
E_{AS}	Single Pulse Avalanche Energy (note1)	900	mJ
I_{AR}	Avalanche Current (note2)	9	A
P_D	Power Dissipation ($T_j = 25^\circ\text{C}$)	150	W
T_j	Junction Temperature(MAX)	150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55~+150	$^\circ\text{C}$
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	-	0.88	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	62.5	$^\circ\text{C/W}$

Electrical Characteristics (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0	900	-	-	V
ΔBVDSS/ΔT _J	Breakdown Voltage Temperature Coefficient	I _D =250μA ,Reference to 25°C	-	1.0	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =900V, V _{GS} =0V	-	-	10	μA
		V _{DS} =720V, T _c =125°C			100	
I _{GSSF}	Gate-body leakage Current, Forward	V _{GS} =+30V, V _{DS} =0V	-	-	100	nA
I _{GSSR}	Gate-body leakage Current, Reverse	V _{GS} =-30V, V _{DS} =0V	-	-	-100	
On Characteristics						
V _{GS(TH)}	Date Threshold Voltage	I _D =250μA,V _{DS} =V _{GS}	3	-	5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	I _D =4.5A,V _{GS} =10V	-	-	1.4	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0, f=1.0MHz	-	2630	-	pF
C _{oss}	Output Capacitance		-	175	-	
C _{rss}	Reverse Transfer Capacitance		-	14	-	
Switching Characteristics						
T _{d(on)}	Turn-On Delay Time	V _{DD} =450V, I _D =9A R _G =25Ω (Note 3,4)	-	50	110	ns
Tr	Turn-On Rise Time		-	120	250	
T _{d(off)}	Turn-Off Delay Time		-	100	210	
T _f	Turn-Off Rise Time		-	75	160	
Q _g	Total Gate Charge	V _{DS} =720,V _{GS} =10V, I _D =9A (Note 3,4)	-	45	58	nC
Q _{gs}	Gate-Source Charge		-	13	-	
Q _{gd}	Gate-Drain Charge		-	18	-	
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Max. Diode Forward Current	-	-	-	9	A
I _{SM}	Max. Pulsed Forward Current	-	-	-	36	
V _{SD}	Diode Forward Voltage	I _D =9A	-	-	1.4	V
T _{rr}	Reverse Recovery Time	I _S =9A,V _{GS} =0V diF/dt=100A/μs	-	690	-	nS
Q _{rr}	Reverse Recovery Charge	(Note3)	-	76	-	μC

Notes : 1, L=20.8mH, IAS=9A, VDD=50V, RG=25Ω, Starting TJ =25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

4, Essentially Independent of Operating Temperature

Typical Characteristics

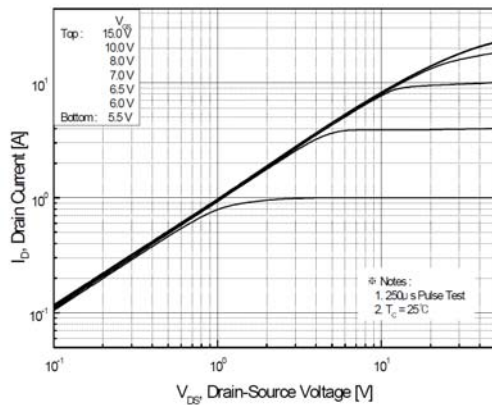


Figure 1. On-Region Characteristics

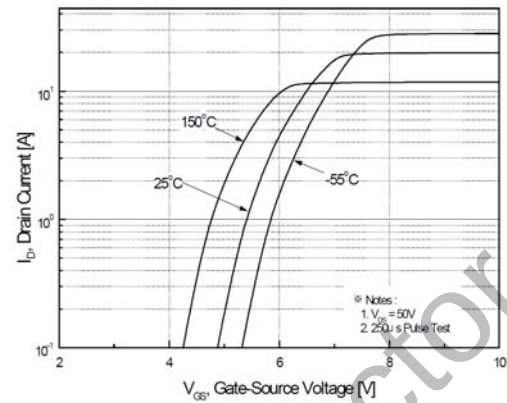


Figure 2. Transfer Characteristics

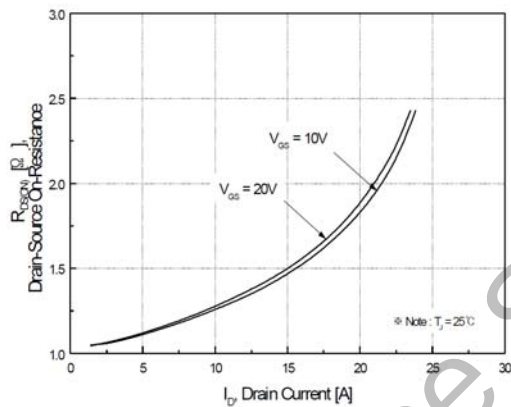


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

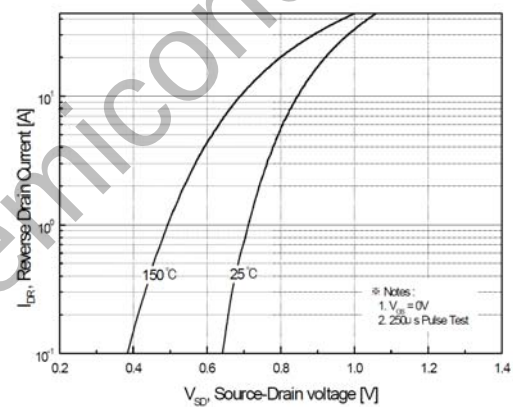


Figure 4. Body Diode Forward Voltage Variation with Source Current

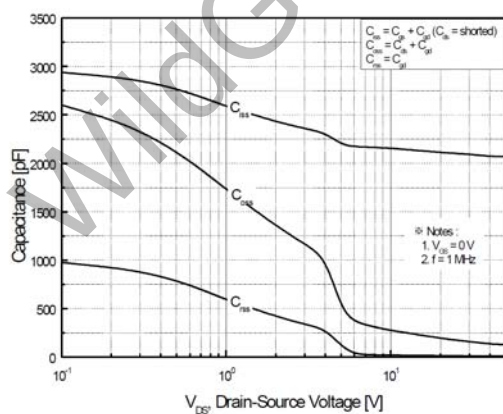


Figure 5. Capacitance Characteristics

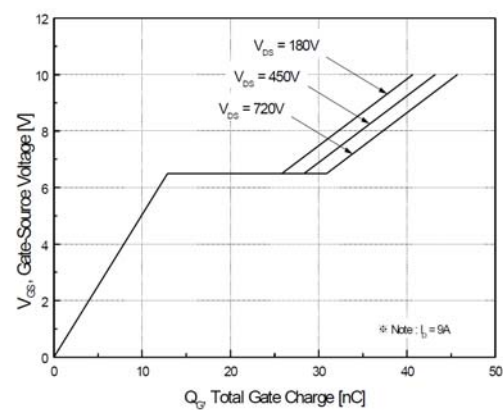


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

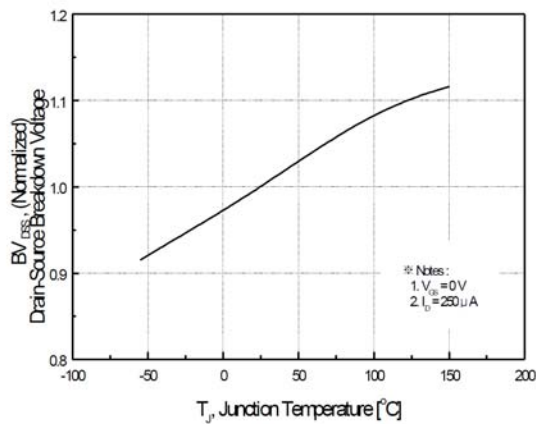


Figure 7. Breakdown Voltage Variation

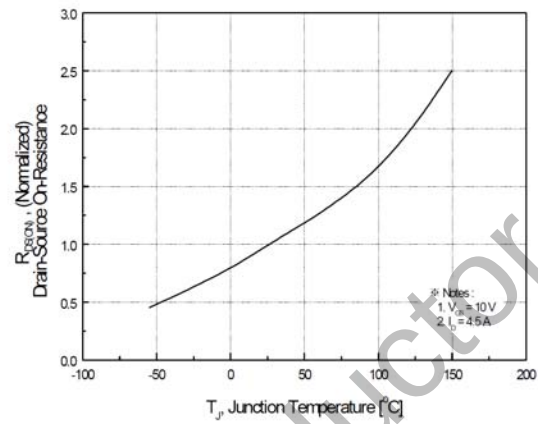


Figure 8. On-Resistance Variation

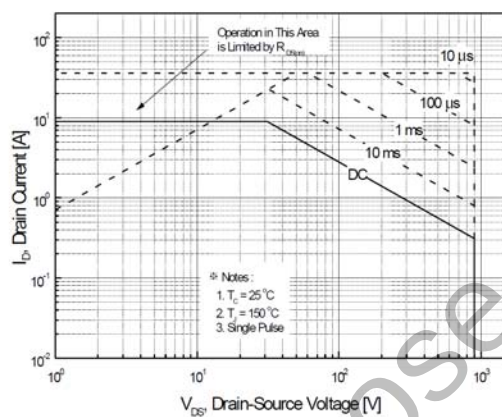


Figure 9. Maximum Safe Operating Area

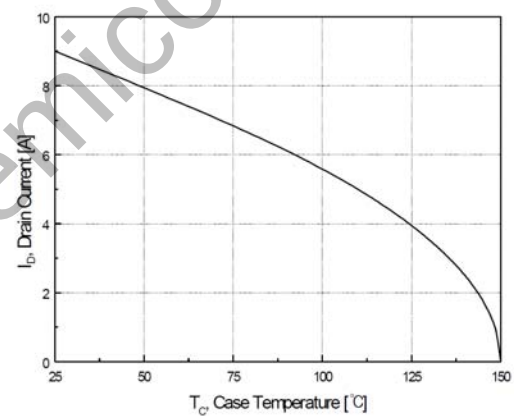


Figure 10. Maximum Drain Current vs Case Temperature

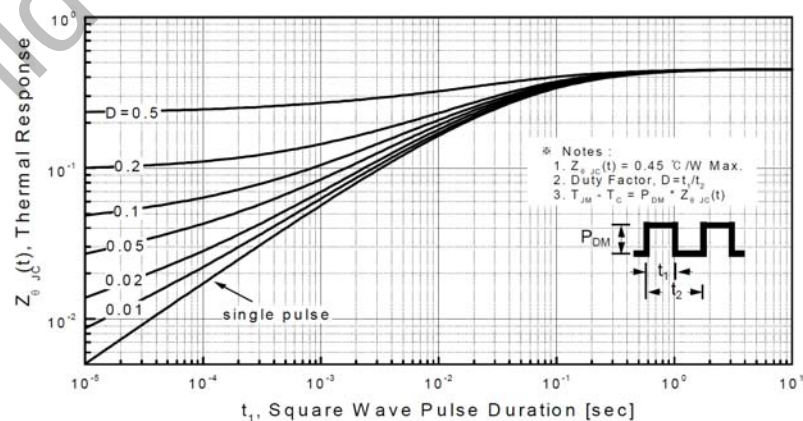
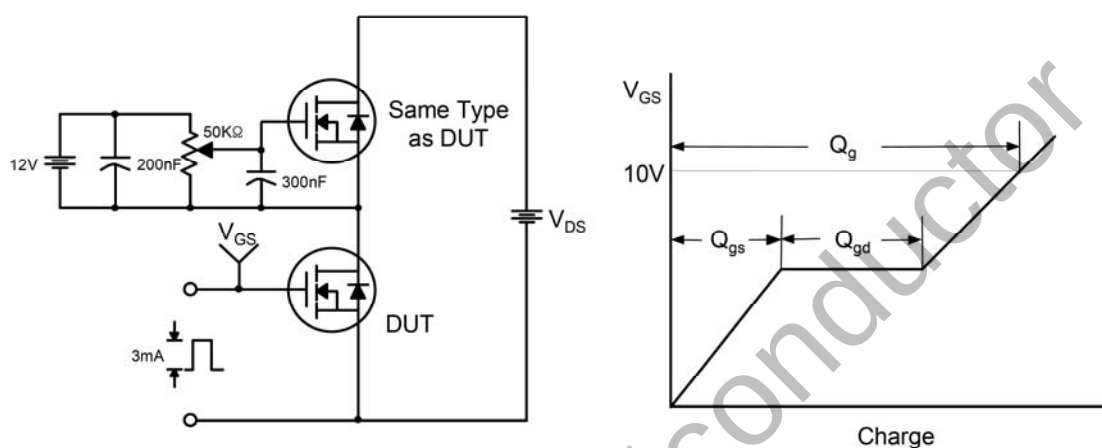
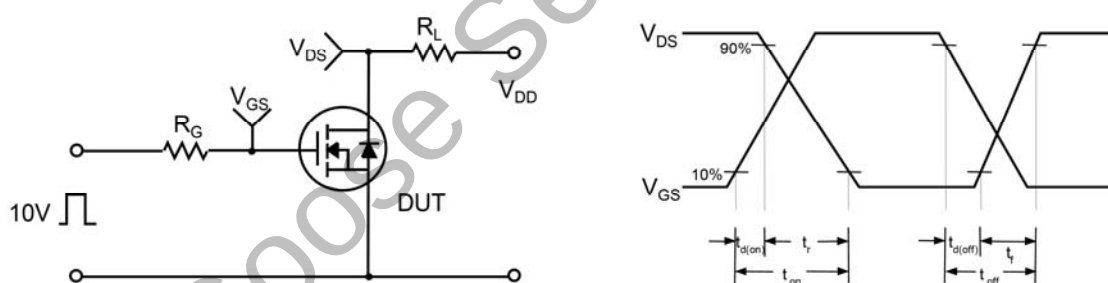


Figure 11. Transient Thermal Response Curve

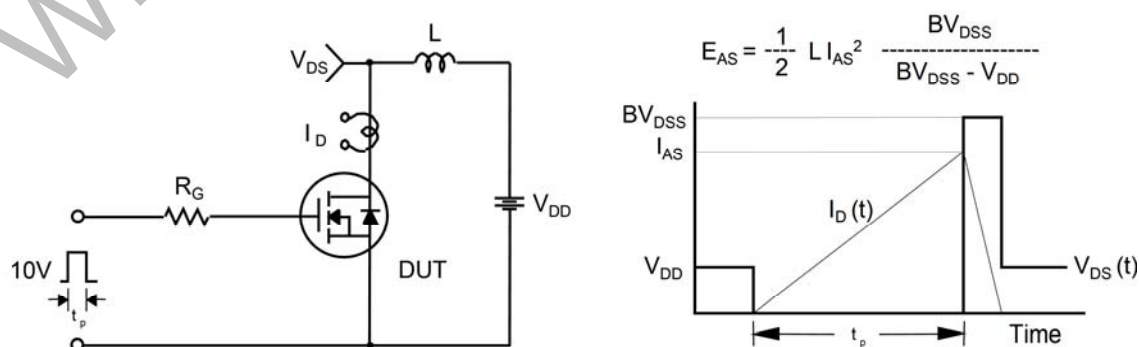
Gate Charge Test Circuit & Waveform



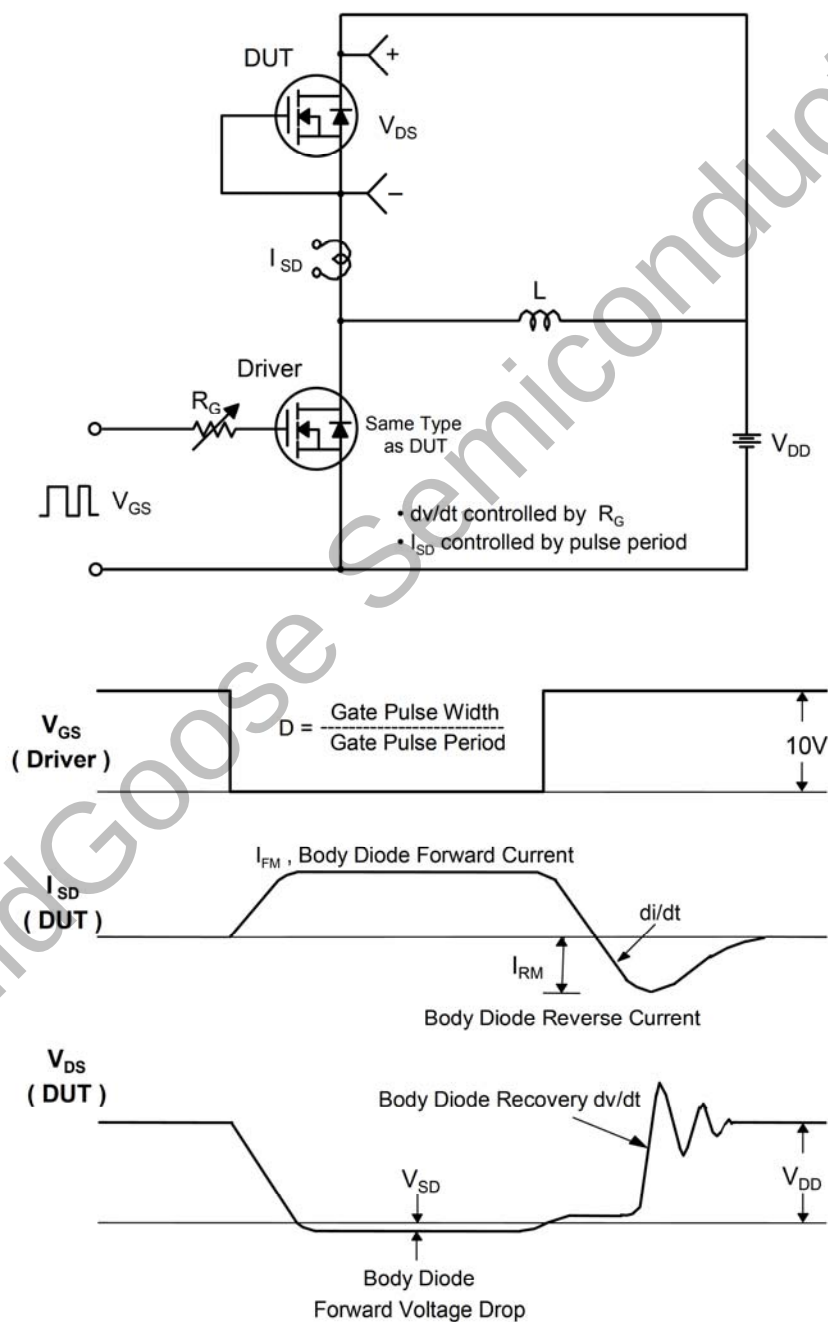
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

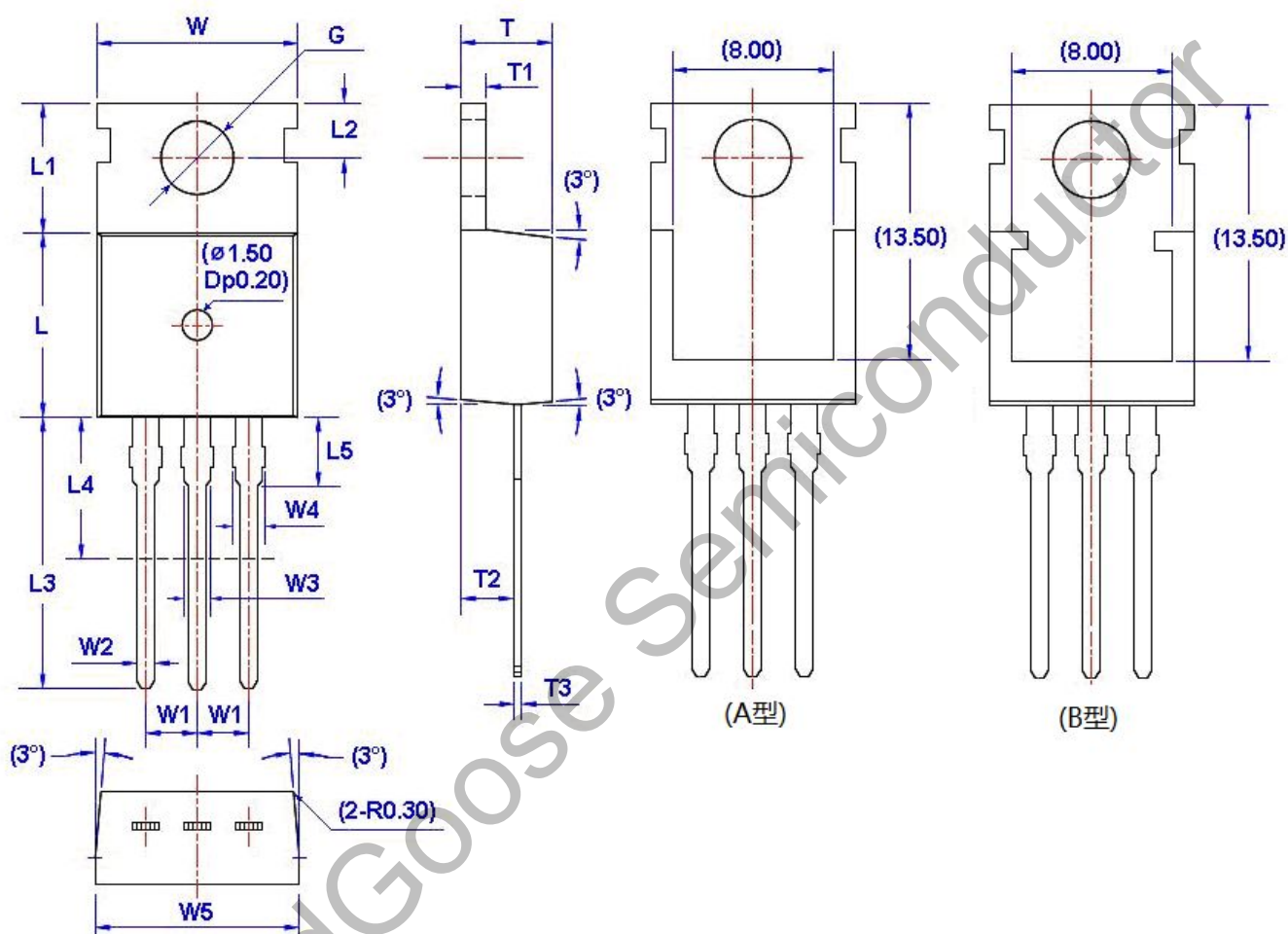


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimension**TO-220**

Unit:mm



Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	9.66	10.28	W5	9.80	10.20	L4**	6.20	6.60	T3	0.45	0.60
W1	2.54 (TYP)		L	9.00	9.40	L5	2.79	3.30	G(Φ)	3.50	3.70
W2	0.70	0.95	L1	6.40	6.80	T	4.30	4.70			
W3	1.17	1.37	L2	2.70	2.90	T1	1.15	1.40			
W4*	1.32	1.72	L3	12.70	14.27	T2	2.20	2.60			